

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	25614	(element or chip or ic or component or die or dye or device) with (curv\$3 or blend\$3 or flexible) with (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:10
L2	1454	1 and (transfer\$3 with method)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 09:54
L3	163	2 and (second) near (wafer or method)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 09:54
L4	659	(element or chip or ic or component or die or dye or device) with (curv\$3 or blend\$3 or flexible) with (second) near (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 09:54
L5	51	4 and (transfer\$3 with method)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 09:54
L6	29505	(element or chip or ic or component or die or dye or device) and (curv\$3 or blend\$3 or flexible) and (substrate or wafer) and (transfer\$3 with method)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:11
L7	14009	6 and (element or chip or ic or component or die or dye or device) with (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:12
L8	1382	6 and (element or chip or ic or component or die or dye or device) with (second) near3 (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:13
L9	747	6 and (element or chip or ic or component or die or dye or device) with (second) near (substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:13

L10	449	6 and (element or chip or ic or component or die or dye or device) with (second) near (substrate or wafer) same (first) near (wafer or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:13
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